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Board for printed circuit with surface mount technology (SMT) components

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Abstract of DE19540814

The board is assembled from a heat-conducting plate (15) and a circuit board (1) to which surface mount devices (SMD) (6), such as microchips, are fixed. The adhesive bond (16) between the plate and circuit board is broken in the vicinity of these devices. The circuit board also incorporates right-angled slots (11-14) around the corners of the devices, leaving sufficient room only for conductive tracks (7-10) to pass between the slots for connections to the solder pads (2-5).

